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09/016599

		Subclass
	Class	ISSUE CLASSIFICATION

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
FA SCANNED <u>4km</u> Q.A. <u>CTH</u>	

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/816599	F	257	61	2826	Giffen

APPLICANTS

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Title

Semiconductor package including stacked chips

PTO-2040
12/99

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
	_____ (Assistant Examiner) _____ (Date)				
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____				ISSUE FEE	
	_____ (Primary Examiner) _____ (Date)			Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	
	_____ (Legal Instruments Examiner) _____ (Date)				

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